

SDB0230G

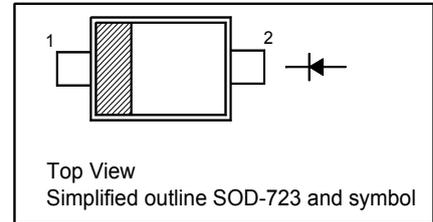
Schottky Barrier Diode

Features

- Low forward voltage drop
- Low reverse current
- Extremely fast switching speed

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	30	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Non-repetitive Peak Forward Surge Current($t = 8.3$ ms)	I_{FSM}	1	A
Power Dissipation	P_D	200	mW
Operating and Storage Temperature Range	T_J, T_{stg}	- 55 to + 125	$^\circ\text{C}$

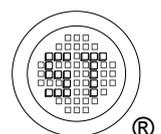
Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ¹⁾	$R_{\theta JA}$	500	$^\circ\text{C/W}$

¹⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 100 \mu\text{A}$	$V_{(BR)R}$	30	-	V
Forward Voltage at $I_F = 10$ mA at $I_F = 200$ mA	V_F	- -	0.325 0.5	V
Reverse Current at $V_R = 10$ V	I_R	-	10	μA



Electrical Characteristics Curves

Fig 1. Reverse Characteristics Curve

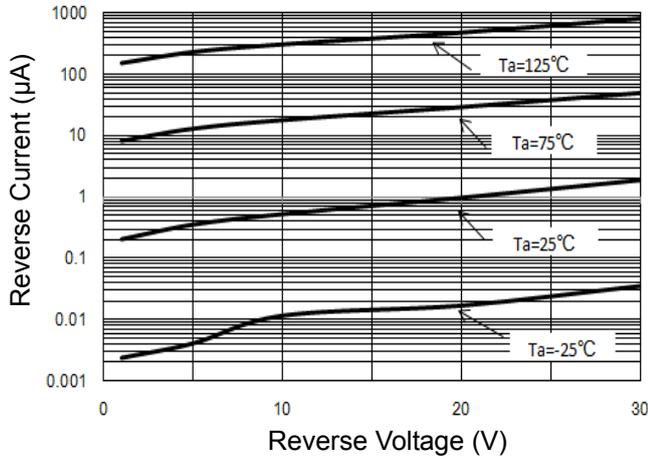


Fig 2. Forward Characteristics Curve

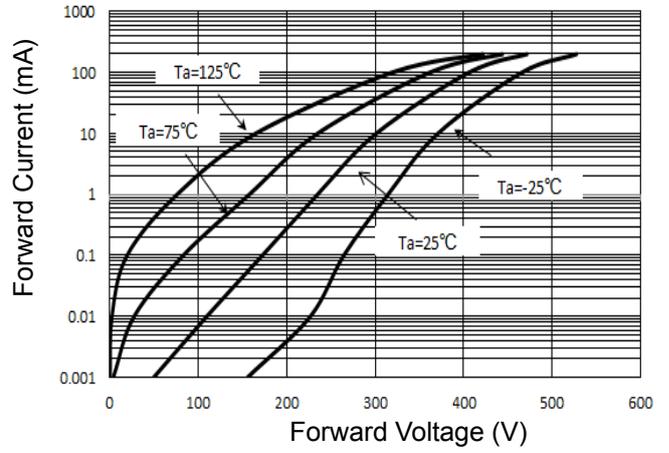


Fig 3. Junction Capacitance

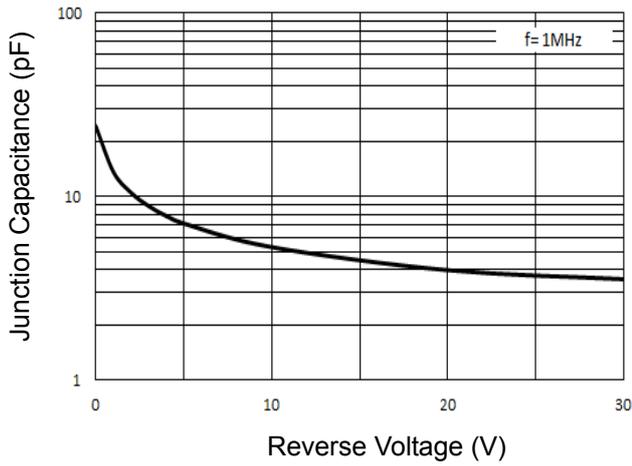
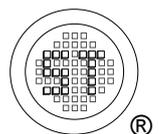
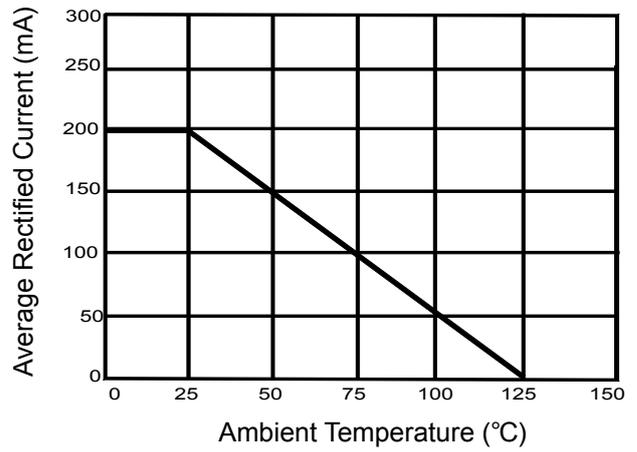


Fig 4. Average Rectified Current Derating Curve

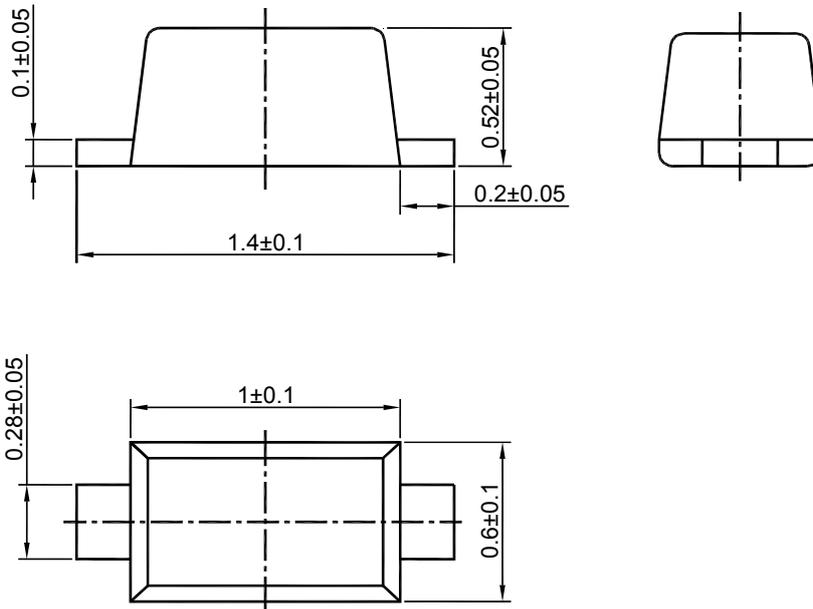


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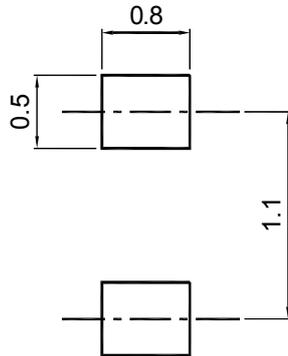
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-723



Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOD-723	8	2 ± 0.1	0.079 ± 0.004	178	7	5,000 10,000

Marking information

" 7C " = Part No.

" III " = Cathode line

Font type: Arial

